



## General Description

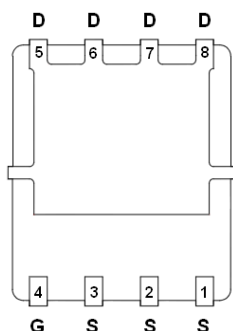
AFN7456S, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

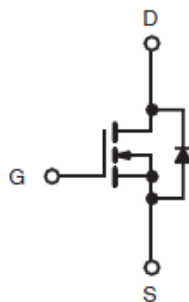
## Features

- $I_D=12A, R_{DS(ON)}= 20m\Omega@V_{GS}=10V$
- $I_D=10A, R_{DS(ON)}= 28m\Omega@V_{GS}=4.5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN 5X6-8L package design

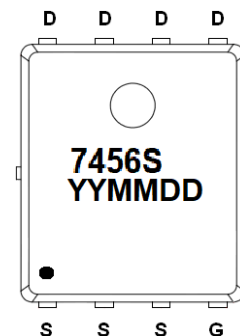
## Pin Description ( DFN 5X6-8L )



BOTTOM VIEW



SYMBOL



TOP VIEW

## Application

- Synchronous Rectification
- DC/DC Primary Side Switch
- Telecom/Server 48 V, Full/Half-Bridge DC/DC
- Quick Charge 2.0/3.0

## Pin Define

Pin	Symbol	Description
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5 ~ 8	D	Drain

## Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN7456SFN568RG	7456S	DFN 5X6-8L	Tape & Reel	2500 EA

※ 7456S : Parts Code

※ YYMMDD : Date Code

※ AFN7456SFN568RG : 13" Tape & Reel ; Pb- Free ; Halogen -Free



### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ Unless otherwise noted)

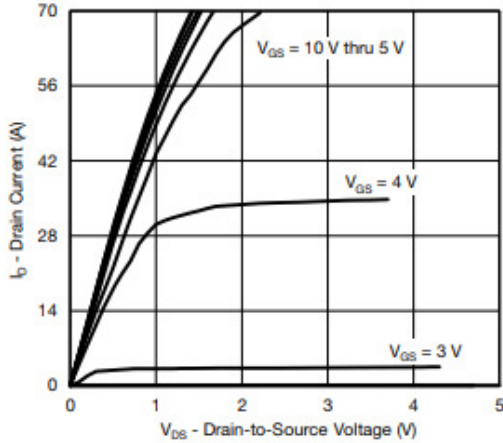
Parameter	Symbol	Typical	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate -Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_J=150^\circ\text{C}$ )	$I_{DSM}$	$T_C=25^\circ\text{C}$	28
		$T_C=70^\circ\text{C}$	24
Pulsed Drain Current ( $t=100\mu\text{s}$ )	$I_{DM}$	$T_A=25^\circ\text{C}$	12
		$T_A=70^\circ\text{C}$	10
Continuous Source Current (Diode Conduction)	$I_S$	$T_C=25^\circ\text{C}$	70
		$T_A=25^\circ\text{C}$	25
Single Pulse Avalanche Current	$I_{AS}$	$L=0.1\text{mH}$	4.5
			$E_{AS}$
Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$	11
		$T_C=75^\circ\text{C}$	36
Operating Junction Temperature	$T_J$	$T_A=25^\circ\text{C}$	5
		$T_A=75^\circ\text{C}$	3.2
Storage Temperature Range	$T_{STG}$	150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	-55/150	$^\circ\text{C}$
Maximum Junction-to-Case (Drain)	$R_{\theta JA}$	25	$^\circ\text{C/W}$
		Steady-State	3.5

### Electrical Characteristics ( $T_A=25^\circ\text{C}$ Unless otherwise noted)

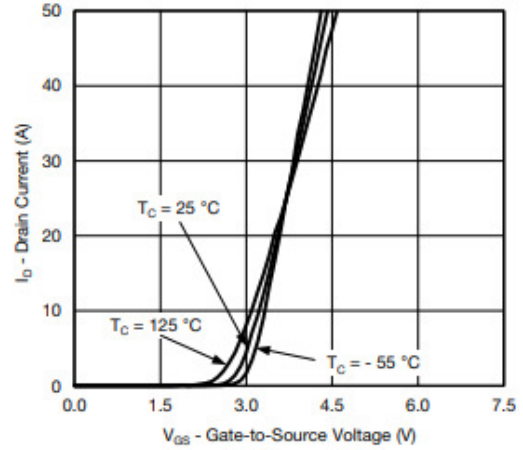
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DS}$	$V_{GS}=0V, I_D=250\mu\text{A}$	100			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0		2.5	
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V$			1	uA
		$V_{DS}=80, V_{GS}=0V$ $T_J=85^\circ\text{C}$			30	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq 5V, V_{GS}=10V$	30			A
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=12A$		16	20	m $\Omega$
		$V_{GS}=4.5V, I_D=10A$		22	28	
Forward Transconductance	$g_{FS}$	$V_{DS}=10, I_D=10A$		26		S
Diode Forward Voltage	$V_{SD}$	$I_S=4A, V_{GS}=0V$		0.75	1.2	V
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{DS}=50V, V_{GS}=4.5V$ $I_D \equiv 10A$		9.5	20	nC
Gate-Source Charge	$Q_{gs}$			2.8		
Gate-Drain Charge	$Q_{gd}$			4.5		
Gate Resistance	$R_g$	$f=1\text{MHz}$	0.2	0.8	1.6	$\Omega$
Input Capacitance	$C_{iss}$	$V_{DS}=50V, V_{GS}=0V$ $f=1\text{MHz}$		900		pF
Output Capacitance	$C_{oss}$			350		
Reverse Transfer Capacitance	$C_{rss}$			30		
Turn-On Time	$t_{d(on)}$	$V_{DD}=50V, R_L=5\Omega$ $I_D \equiv 10A, V_{GEN}=10V$ $R_G=1\Omega$		12	25	ns
	$t_r$			10	20	
Turn-Off Time	$t_{d(off)}$			20	40	
	$t_f$			10	20	



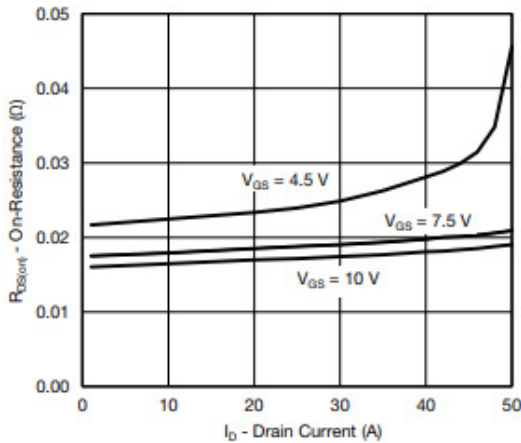
## Typical Characteristics



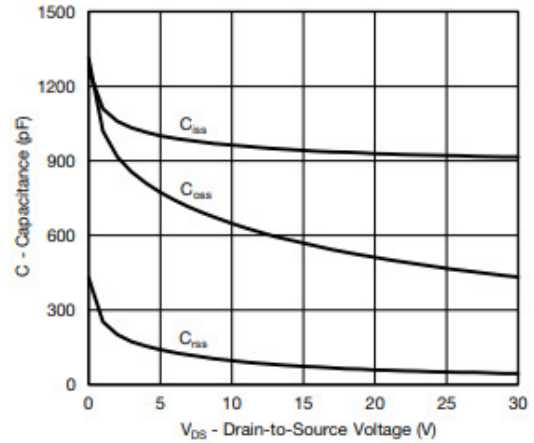
Output Characteristics



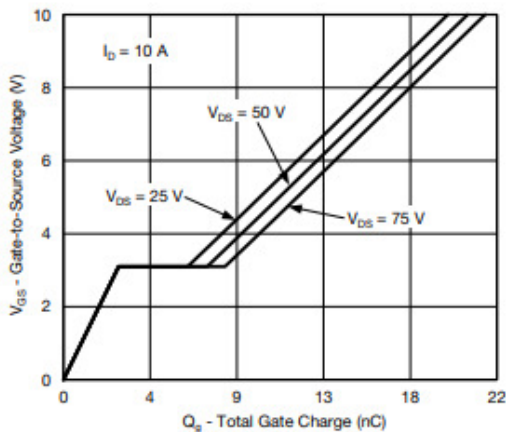
Transfer Characteristics



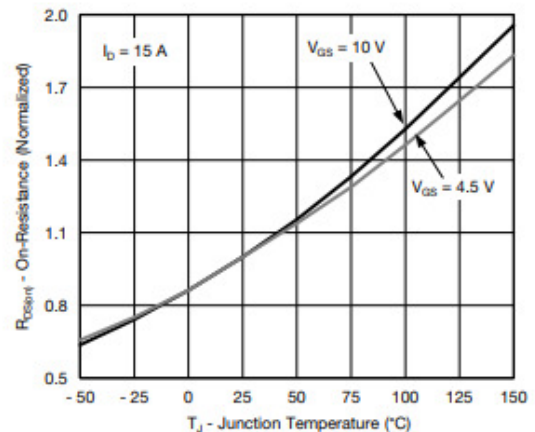
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



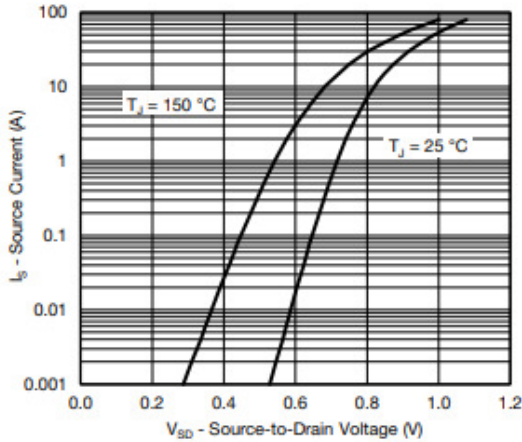
Gate Charge



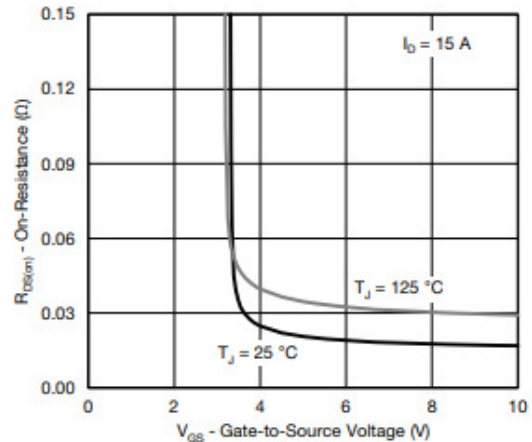
On-Resistance vs. Junction Temperature



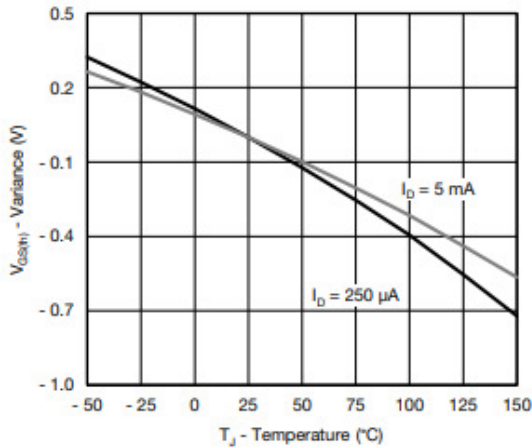
## Typical Characteristics



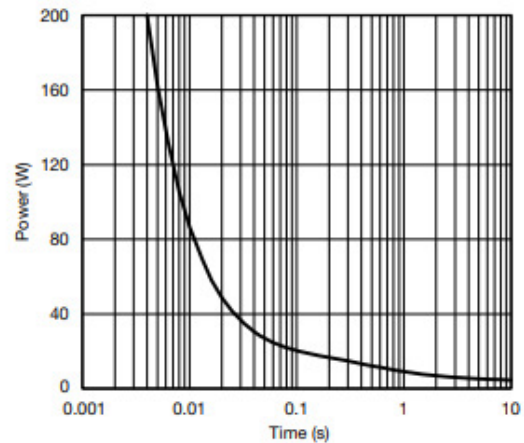
Source-Drain Diode Forward Voltage



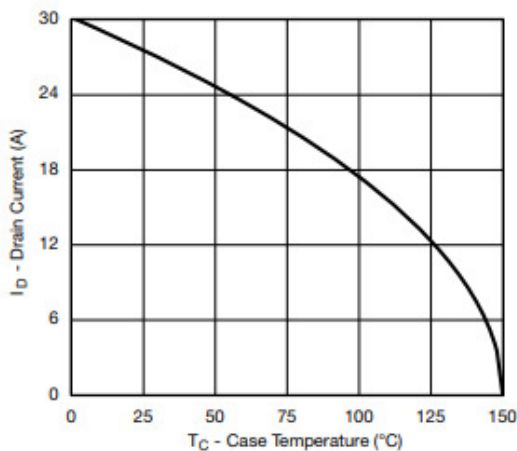
On-Resistance vs. Gate-to-Source Voltage



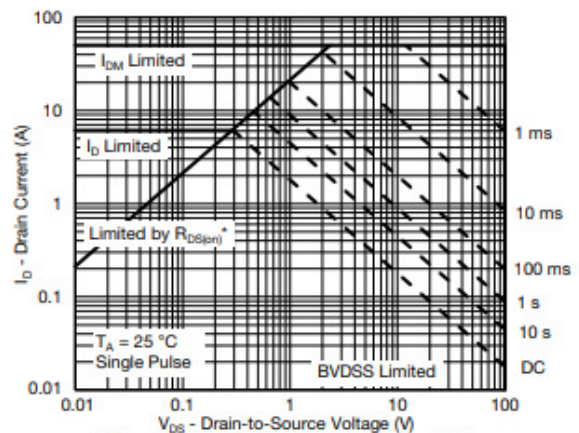
Threshold Voltage



Single Pulse Power, Junction-to-Ambient



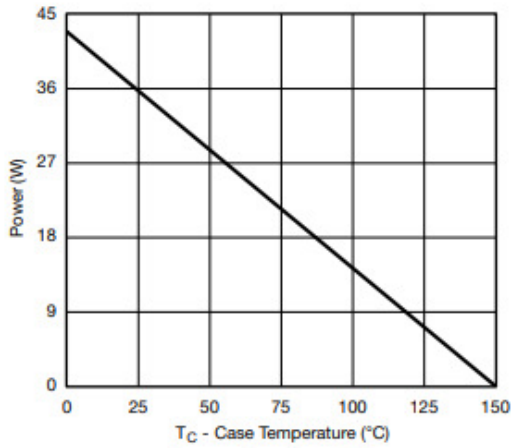
Current Derating\*



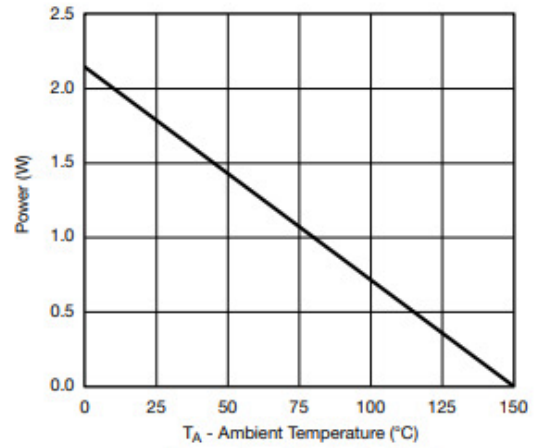
Safe Operating Area, Junction-to-Ambient



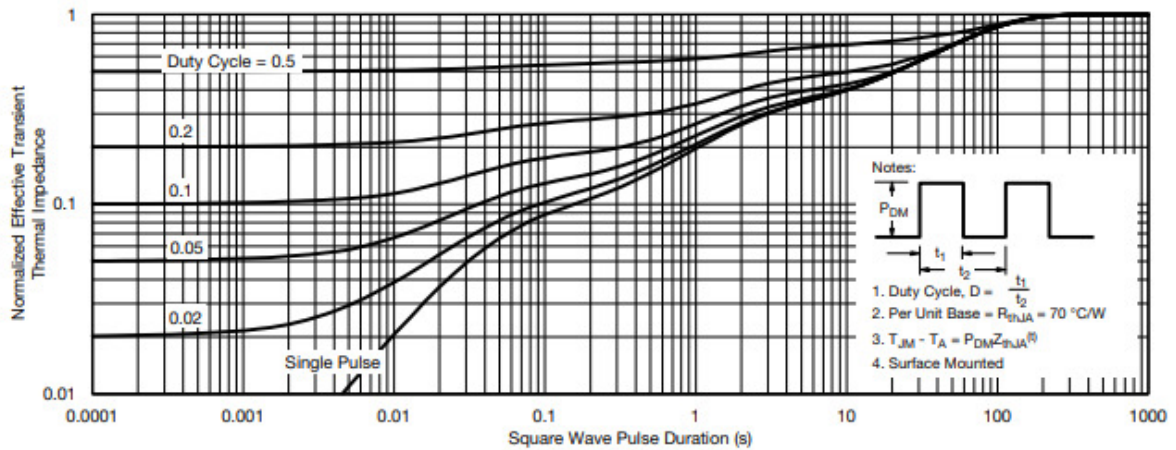
## Typical Characteristics



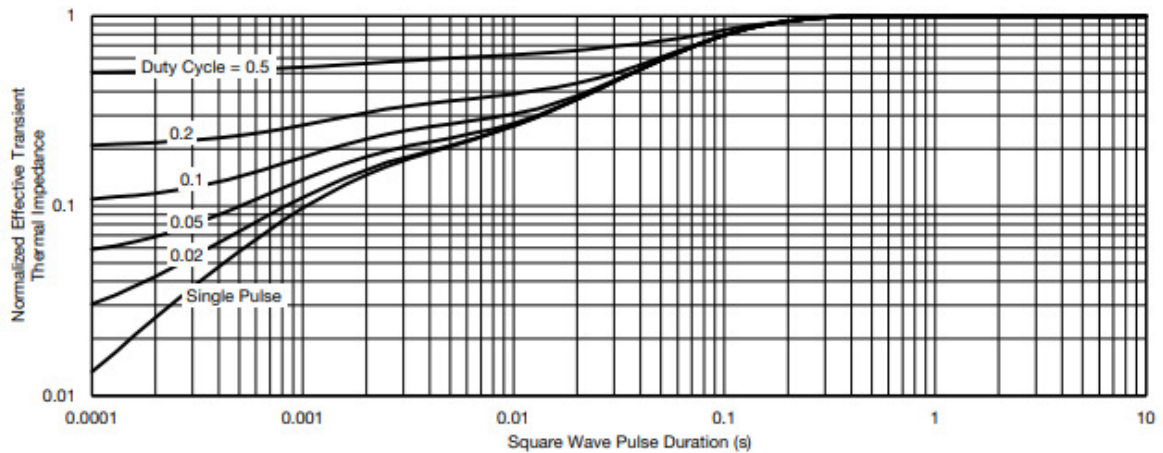
Power, Junction-to-Case



Power, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient



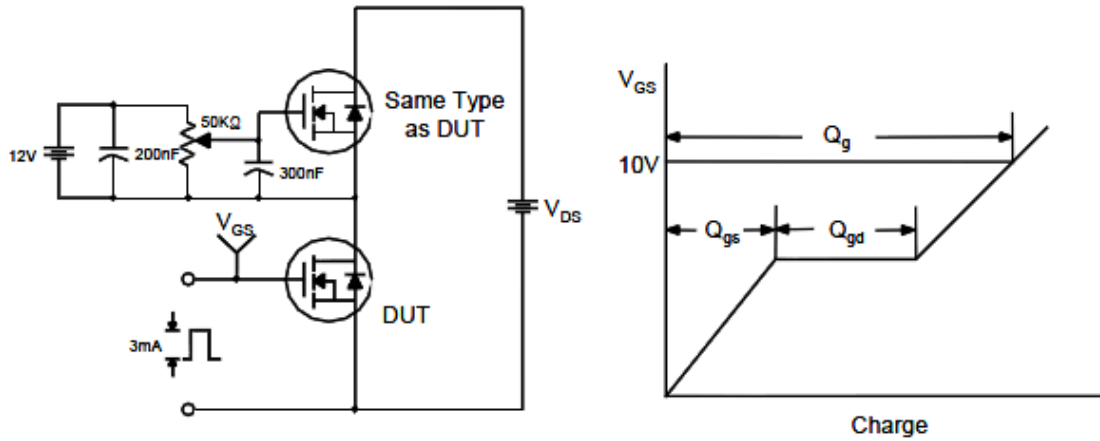
Normalized Thermal Transient Impedance, Junction-to-Case



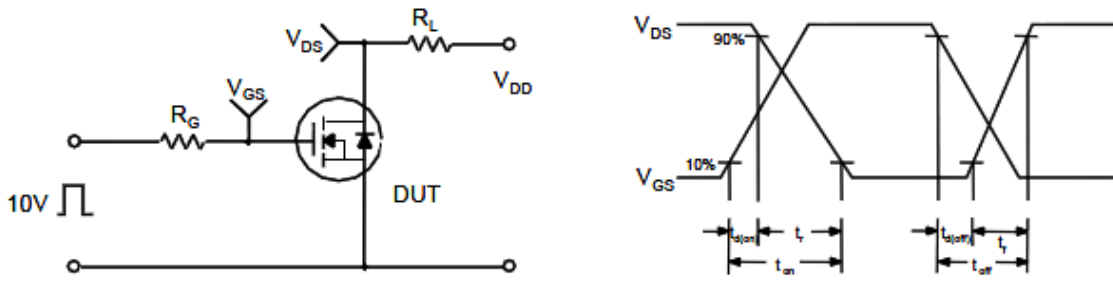


**Typical Characteristics**

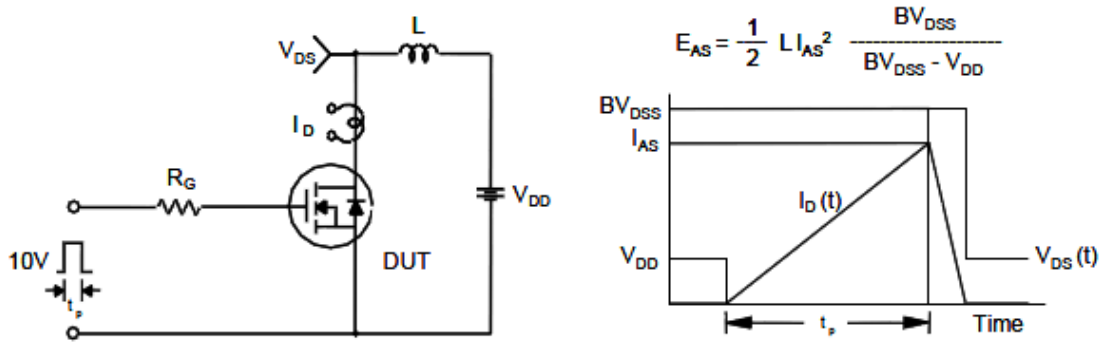
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

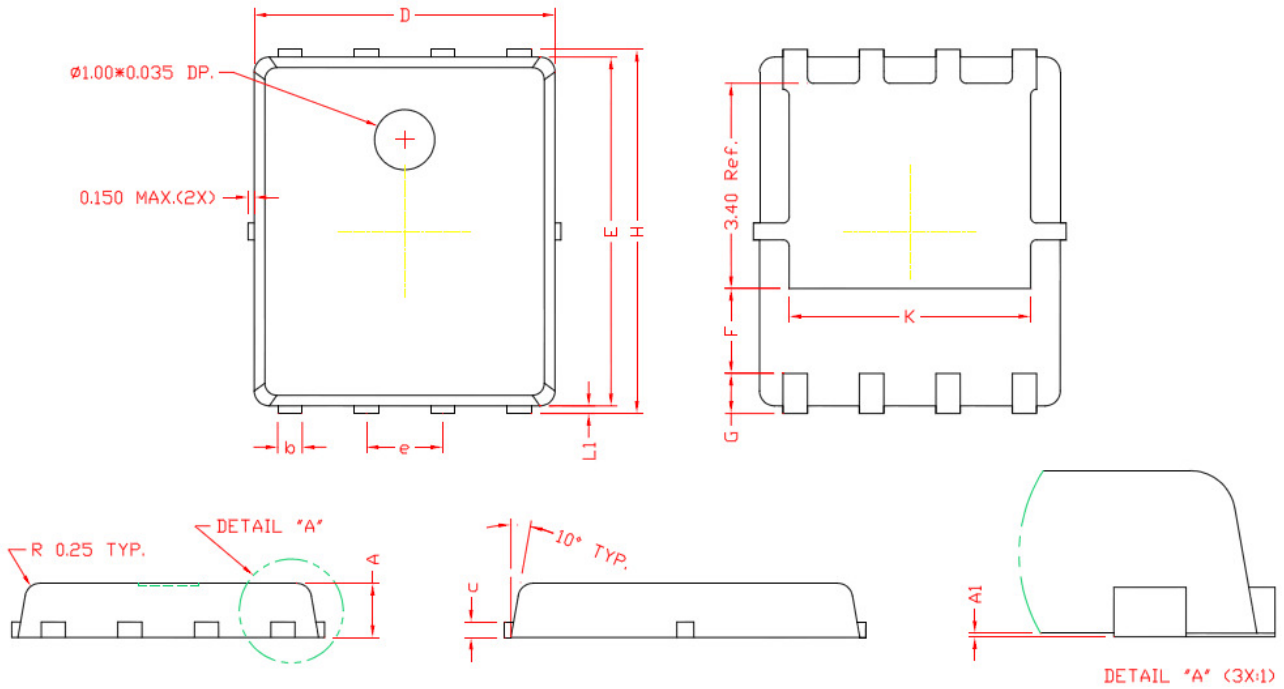


Unclamped Inductive Switching Test Circuit & Waveforms





**Package Information ( DFN 5X6-8L )**



**DIMENSIONS**

REF.	Millimeters		REF.	Millimeters	
	Min.	Max.		Min.	Max.
A	0.80	1.00	E	5.70	5.90
A1	0.00	0.05	e	1.27 BSC.	
b	0.35	0.49	H	5.95	6.20
c	0.254 Ref.		L1	0.10	0.18
D	4.90	5.10	G	0.60 Ref.	
F	1.40 Ref.		K	4.00 Ref.	

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